

NEGATIVE PHOTSENSITIVE RESIN COMPOSITION, CURED PRODUCT
AND METHOD FOR PRODUCING SAME, HOLLOW STRUCTURE, ELECTRONIC
COMPONENT, AND ELASTIC WAVE FILTER

ABSTRACT

The present invention has been devised with a challenge to provide a negative photosensitive resin composition capable of affording a cured product superior in low residual stress and low water absorption. The present invention is a negative photosensitive resin composition including: a polyimide resin (A) containing one or more skeletons selected from the group consisting of an alkyleneoxy skeleton, a siloxane skeleton, and an aliphatic hydrocarbon skeleton having a linear structure; a cationically polymerizable compound (B); and a cationic polymerization initiator (C).

[No Available Figure]